



## Material Content Data Sheet



<b>Sales Product Name</b>		BFN 19 H6327		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001211940						
<b>Package</b>		PG-SOT89-4-3		<b>Weight*</b>		53.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.160	0.30	0.30	3009	3009
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		475	
	non noble metal	chromium	7440-47-3	0.076	0.14		1424	
wire	non noble metal	copper	7440-50-8	25.112	47.28	47.48	472799	474793
	non noble metal	copper	7440-50-8	0.013	0.02	0.02	248	248
	encapsulation	organic material	carbon black	1333-86-4	0.268	0.51		5055
encapsulation	plastics	epoxy resin	-	4.027	7.58		75822	
	inorganic material	silicondioxide	60676-86-0	22.552	42.46	50.55	424602	505479
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15087	15087
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1384	1384
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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